

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention	Solder Film Manufacturing Method, Heat Sink Furnished with Solder Film, and Semiconductor-Device-and-Heat-Sink Junction
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Application Number :

Date :

First Named Applicant: Mr. Katsuhiro Itakura

Attorney Docket Number: 39.036

TOTAL FEE AUTHORIZED \$ 1212

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
Subtotal For Basic Filing Fees: \$ 770			

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 28	8	1202	18	144
Independent Claims : 6	3	1201	86	258
Subtotal For Extra Claims Fees: \$ 402				

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

AUTHORIZED BILLING INFORMATION

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Credit account number: 3014

Expiration Date (YYYYMMDD): 2009-04-30

Authorized name: JAMES W JUDGE

Billing address: 99999